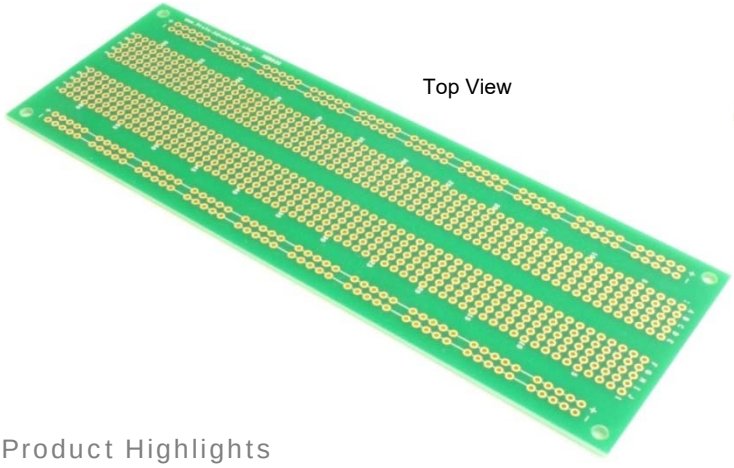
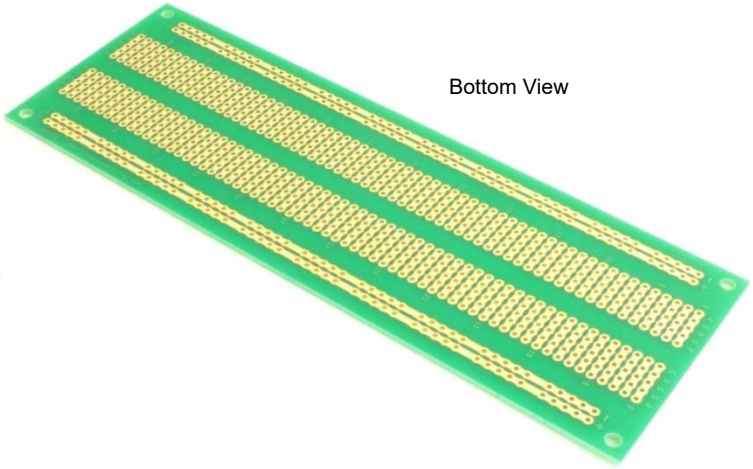
# SBB830 Proto Advantage

Datasheet revision 1.4 www.Proto-Advantage.com

## 830 pts solder-in breadboard (Exact Solderless Match)


Top View


Bottom View

### Product Highlights

Immersion Gold Finish
All holes are gold plated and are on a 0.1" grid
1/16” (1.6mm) thick FR-4 UL94V-0
Accepts a variety of wire sizes (20-32 AWG)
4 mounting holes

### Usage

This board exactly copies the routing of an 830 pts full size solderless breadboard.

Allows direct transfer of circuits prototyped in a solderless breadboard to a solder-in breadboard to facilitate functional in-system testing or field testing.

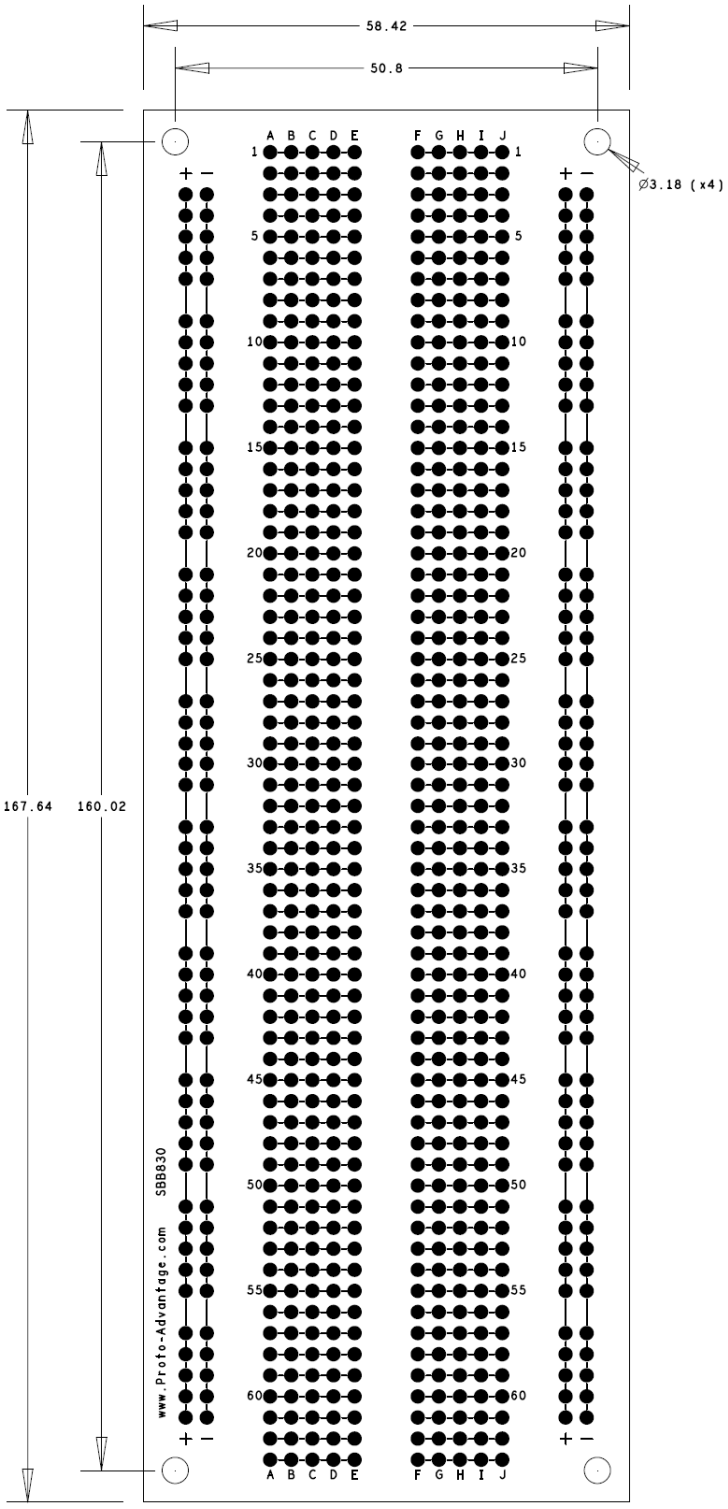
### Specifications

| | |
|---|---|
| Wiring Pattern: | 2 Distribution Strips<br>1 Terminal Strip<br>200 Distribution Holes<br>630 Terminal Holes |
| Dimensions: | 6.6" x 2.3" x 0.0625" (167.64mm x 58.42mm x 1.6mm) |
| PCB construction: | FR-4 UL94V-0 |
| PCB operating temperature range: | -40°C to +130°C (-40°F to +266°F) |
| PCB reflow maximum temperature: | +260°C (500°F) |
| PCB trace width: | 0.059” (1.5mm) |
| PCB trace thickness: | 1 oz copper / $ft^2$ (1.4 mils) (0.03556 mm) |
| PCB trace current capacity*: | 10A continuous @ 40°C rise, 13A continuous @ 80°C rise* |
| Hole size: | 1.0mm (40 mils) diameter |
| Recommended pin size: | 25 mil square wire wrap posts or smaller |
| Diameter of 4 corner mounting holes: | 3.2mm (125 mils) |

* Derived from IPC-2221 current capacity graphs at 25°C ambient temperature. Actual current capacity will vary based on air flow, component density, and other factors.

Top View of SBB830

Topside silkscreen lines between holes show where bottom traces electrically connect holes.




(Representative drawing only - not to scale)